



Material Content Data Sheet



Sales Product Name		TLE94108EL		Issued		24. January 2018		
MA#		MA001658658						
Package		PG-SSOP-24-9		Weight*		150.84 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.240	2.15	2.15	21480	21480
leadframe	inorganic material	phosphorus	7723-14-0	0.017	0.01		111	
	non noble metal	zinc	7440-66-6	0.067	0.04		446	
	non noble metal	iron	7439-89-6	1.345	0.89		8917	
wire	non noble metal	copper	7440-50-8	54.617	36.21	37.15	362087	371561
	non noble metal	copper	7440-50-8	0.853	0.57	0.57	5657	5657
	encapsulation	organic material	carbon black	1333-86-4	0.173	0.11		1148
plastics	plastics	epoxy resin	-	7.965	5.28		52806	
	inorganic material	silicondioxide	60676-86-0	78.440	52.00	57.39	520025	573979
leadfinish	non noble metal	tin	7440-31-5	2.911	1.93	1.93	19298	19298
plating	noble metal	silver	7440-22-4	0.234	0.16	0.16	1553	1553
glue	plastics	epoxy resin	-	0.244	0.16		1618	
	noble metal	silver	7440-22-4	0.732	0.49	0.65	4854	6472
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com